



SES22533-60 A/B

Product Description

Shin-Etsu's SES22533-60 A/B is a dual component, room-temperature cure, self leveling potting encapsulant that cures to form a durable, flexible rubber to protect electronic components. SES22533-60 A/B exhibits excellent unprimed adhesion to most circuit board substrates, metals, plastics, glass, and ceramics.

Product Features

- Dual component
- 1:1 mix ratio
- Room-temperature cure
- Self-leveling

Typical Applications

- Protecting and electrically isolating electronic components
- Stress reduction

Typical Properties

Type	Potting Encapsulant
One/Two Component	Two
UL	HB
Color	Transparent / Black
Density @ 23C (g/cm ³)	0.97
Viscosity A (cps)	520.00
Viscosity B (cps)	290.00
Mix Ratio by weight	100:100
Cure Conditions	24hr @ 23C
Snap Time (min)	9
Shore 00 Hardness	60
Usable Temperature Range (C)	-40C to +180C
Durometer @ 23°C 30min / 24h (Shore 00)	43 / 54
AL Cohesive Failure (%)	100

Note: Values are not for specification purposes.

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